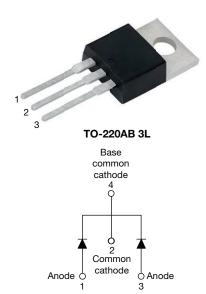


# HEXFRED® Ultrafast Soft Recovery Diode, 2 x 15 A



PRIMARY CHARACTERISTICS								
I <sub>F(AV)</sub>	2 x 15 A							
V <sub>R</sub>	600 V							
V <sub>F</sub> at I <sub>F</sub>	1.2 V							
t <sub>rr</sub> typ.	19 ns							
Package	TO-220AB 3L							
T <sub>J</sub> max.	150 °C							
Circuit configuration	Common cathode							

## **FEATURES**

- · Ultrafast and ultrasoft recovery
- Very low I<sub>RRM</sub> and Q<sub>rr</sub>

Very low I<sub>RRM</sub> and Q<sub>rr</sub>
 Designed and qualified according to JEDEC®-JESD47

HOHS
COMPLIANT HALOGEN
FREE

 Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

#### **BENEFITS**

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- · Reduced parts count

#### **DESCRIPTION**

VS-HFA30TA60C... is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 15 A per leg continuous current, the VS-HFA30TA60C... is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I<sub>RRM</sub>) and does not exhibit any tendency to "snap-off" during the tb portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA30TA60C... is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

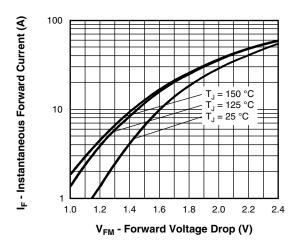
ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Cathode to anode voltage	$V_{R}$		600	V					
Maximum continuous forward current per leg		T 100 °C	15						
per device	I <sub>F</sub>	T <sub>C</sub> = 100 °C	30	^					
Single pulse forward current	I <sub>FSM</sub>		150	Α					
Maximum repetitive forward current	I <sub>FRM</sub>		60						
Maximum navvar discination	Б	T <sub>C</sub> = 25 °C	74	10/					
Maximum power dissipation	$P_{D}$	T <sub>C</sub> = 100 °C	29	W					
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +150	°C					



<b>ELECTRICAL SPECIFICATIONS PER LEG</b> (T <sub>J</sub> = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Cathode to anode breakdown voltage	V <sub>BR</sub>	I <sub>R</sub> = 100 μA	600	-	-				
Maximum forward voltage		I <sub>F</sub> = 15 A		-	1.3	1.7	V		
	$V_{FM}$	I <sub>F</sub> = 30 A	See fig. 1	-	1.5	2.0			
		I <sub>F</sub> = 15 A, T <sub>J</sub> = 125 °C		-	1.2	1.6			
Maximum reverse		$V_R = V_R$ rated		-	1.0	10			
leakage current	I <sub>RM</sub>	$T_J = 125 ^{\circ}\text{C},  V_R = 0.8 ^{\circ}\text{X} ^{\circ}\text{V}_R ^{\circ}\text{rated}$	See fig. 2	-	400	1000	μΑ		
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 200 V See fig. 3		-	25	50	pF		
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from p	-	8	-	nΗ			

<b>DYNAMIC RECOVERY CHARACTERISTICS PER LEG</b> (T <sub>J</sub> = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS			
	t <sub>rr</sub>	$I_F = 1.0 \text{ A}, dI_F/dt = 200 \text{ A}$	-	19	-				
Reverse recovery time See fig. 5 and fig. 10	t <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	42	60	ns		
occ lig. o and lig. To	t <sub>rr2</sub>	T <sub>J</sub> = 125 °C		-	70	120			
Peak recovery current	I <sub>RRM1</sub>	T <sub>J</sub> = 25 °C		-	4.0	6.0	- A - nC - A/μs		
See fig. 6	I <sub>RRM2</sub>	T <sub>J</sub> = 125 °C	I <sub>F</sub> = 15 A	-	6.5	10			
Reverse recovery charge	Q <sub>rr1</sub>	T <sub>J</sub> = 25 °C	dl <sub>F</sub> /dt = 200 A/μs V <sub>B</sub> = 200 V	-	80	180			
See fig. 7	Q <sub>rr2</sub>	T <sub>J</sub> = 125 °C	V <sub>R</sub> = 200 V	-	220	600			
Peak rate of fall of	dI <sub>(rec)M</sub> /dt1	T <sub>J</sub> = 25 °C		-	250	-			
recovery current during t <sub>b</sub> See fig. 8	dI <sub>(rec)M</sub> /dt2	T <sub>J</sub> = 125 °C		-	160	-			

THERMAL - MECHANICAL SPECIFICATIONS PER LEG										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Lead temperature	T <sub>lead</sub>	0.063" from case (1.6 mm) for 10 s	-	-	300	°C				
Junction to case, single leg conducting	D				1.7					
Junction to case, both legs conducting	- R <sub>thJC</sub>		-	-	0.85	12 001				
Thermal resistance, junction to ambient	R <sub>thJA</sub>	Typical socket mount	-	-	40	K/W				
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	-	0.25	-					
Maight			=.	6.0	-	g				
Weight			-	0.21	-	OZ.				
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)				
Marking device		Case style 3L TO-220AB	HFA30TA60C							



10 000 T<sub>.1</sub> = 150 °C I<sub>R</sub> - Reverse Current (µA) 1000 100 10 T<sub>J</sub> = 25 °C 0.1 0.01 200 100 300 400 500 600 0 V<sub>R</sub> - Reverse Voltage (V)

Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

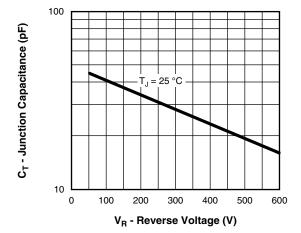


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

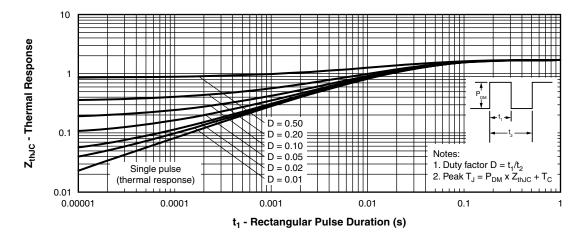


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics (Per Leg)

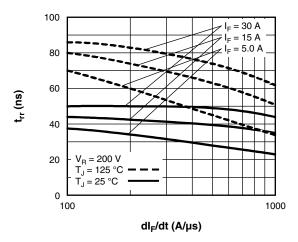


Fig. 5 - Typical Reverse Recovery Time vs. dl<sub>E</sub>/dt (Per Leg)

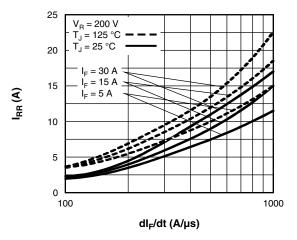


Fig. 6 - Typical Recovery Current vs. dl<sub>F</sub>/dt (Per Leg)

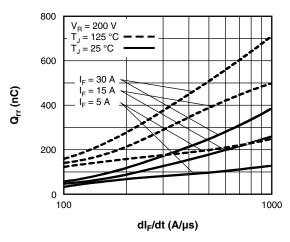


Fig. 7 - Typical Stored Charge vs. dl<sub>F</sub>/dt (Per Leg)

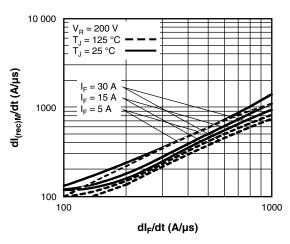
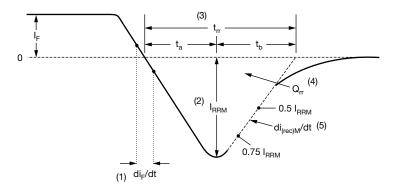


Fig. 8 - Typical dl<sub>(rec)M</sub>/dt vs. dl<sub>F</sub>/dt (Per Leg)



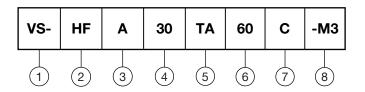
- di<sub>F</sub>/dt rate of change of current through zero crossing
- (2)  $I_{RRM}$  peak reverse recovery current
- (3) t<sub>rr</sub> reverse recovery time measured from zero crossing point of negative going I<sub>F</sub> to point where a line passing through 0.75 I<sub>RRM</sub> and 0.50 I<sub>RRM</sub> extrapolated to zero current.
- (4)  $\mathbf{Q}_{\rm rr}$  area under curve defined by  $\mathbf{t}_{\rm rr}$  and  $\mathbf{I}_{\rm RRM}$ 
  - $Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$
- (5)  $di_{(rec)M}/dt$  peak rate of change of current during  $t_{b}$  portion of  $t_{rr}$

Fig. 9 - Reverse Recovery Waveform and Definitions



## **ORDERING INFORMATION TABLE**

Device code



Vishay Semiconductors product

- HEXFRED® family

3 - Electron irradiated

Current rating (30 = 30 A)

5 - Package:

TA = 3L TO-220AB

6 - Voltage rating (60 = 600 V)

Circuit configuration:
C = common cathode

8 - Environmental digit:

-M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free

ORDERING INFORMATION (Example)									
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION							
VS-HFA30TA60C-M3	50	Antistatic plastic tube							

LINKS TO RELATED DOCUMENTS							
Dimensions <u>www.vishay.com/doc?96154</u>							
Part marking information	www.vishay.com/doc?95028						



## **TO-220AB 3L**

## **DIMENSIONS** in millimeters and inches





Conforms to JEDEC® outline TO-220AB

SYMBOL	MILLIM	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES	NOTES	STIVIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.25	4.65	0.167	0.183			D2	11.68	13.30	0.460	0.524	6, 7
A1	1.14	1.40	0.045	0.055			Е	10.11	10.51	0.398	0.414	3, 6
A2	2.50	2.92	0.098	0.115			E1	6.86	8.89	0.270	0.350	6
b	0.69	1.01	0.027	0.040			е	2.41	2.67	0.095	0.105	
b1	0.38	0.97	0.015	0.038	4		e1	4.88	5.28	0.192	0.208	
b2	1.20	1.73	0.047	0.068			H1	6.09	6.48	0.240	0.255	6
b3	1.14	1.73	0.045	0.068	4		L	13.52	14.02	0.532	0.552	
С	0.36	0.61	0.014	0.024			L1	3.32	3.82	0.131	0.150	2
c1	0.36	0.56	0.014	0.022	4		ØΡ	3.54	3.91	0.139	0.154	
D	14.85	15.35	0.585	0.604	3		Q	2.60	3.00	0.102	0.118	
D1	8.38	9.02	0.330	0.355								

## **Notes**

- <sup>(1)</sup> Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3, and c1 apply to base metal only
- Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2, and E1
- (7) Outline conforms to JEDEC® TO-220, except D2



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